



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re Application of

Seigi AOYAMA et al.

Application S/N 09/892,630

Filed: June 28, 2001

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: Art Unit: 2827
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: Examiner: T. Dinh
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For: LEAD-FREE SOLDER, AND CONNECTION LEAD AND ELECTRICAL
COMPONENT USING SAID LEAD-FREE SOLDER

REQUEST FOR RECONSIDERATION

Honorable Assistant Commissioner
for Patents
Washington, DC 20231

Sir:

This Request for Reconsideration is filed concurrently with the filing of a Request for Continued Examination and further to the Amendment filed on March 19, 2003, and the Advisory Action issued on May 6, 2003.